

## ABSTRACT

5       An interconnect for testing semiconductor components  
includes a substrate, and contacts on the substrate for  
making temporary electrical connections with bumped contacts  
on the components. Each contact includes a recess and a  
pattern of leads cantilevered over the recess configured to  
10       electrically engage a bumped contact. The leads are adapted  
to move in a z-direction within the recess to accommodate  
variations in the height and planarity of the bumped  
contacts. In addition, the leads can include projections for  
penetrating the bumped contacts, a non-bonding outer layer  
15       for preventing bonding to the bumped contacts, and a curved  
shape which matches a topography of the bumped contacts. The  
leads can be formed by forming a patterned metal layer on the  
substrate, by attaching a polymer substrate with the leads  
thereon to the substrate, or by etching the substrate to form  
20       conductive beams.